

FEATURES

- | 1100Watts peak pulse power ($t_p = 8/20\mu s$)
- | Unidirectional configurations
- | Solid-state silicon-avalanche technology
- | Operating Voltage: 6.5 V
- | Low clamping voltage
- | Low leakage current

APPLICATIONS

- | Cell Phone Handsets and Accessories
- | Microprocessor based equipment
- | Personal Digital Assistants (PDA's)
- | Notebooks, Desktops, and Servers
- | Portable Instrumentation



DFN1610



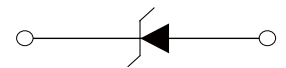
Marking

IEC COMPATIBILITY

- | IEC61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- | IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003



Schematic Symbol

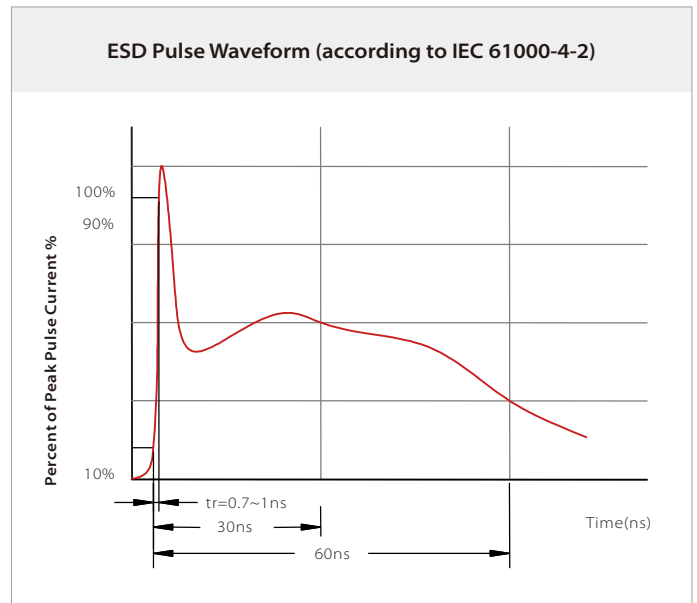
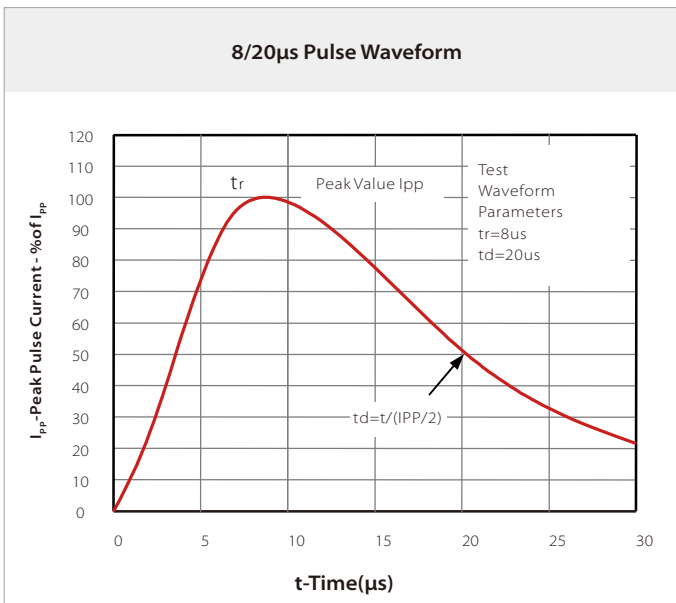
THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
P_{PP}	Peak Pulse Power ($t_p=8/20\mu s$ waveform)	1100	Watts
T_J	Operating Temperature Range	-55 to +125	$^{\circ}C$
T_{STG}	Storage Temperature Range	-55 to +125	$^{\circ}C$

ELECTRICAL CHARACTERISTICS

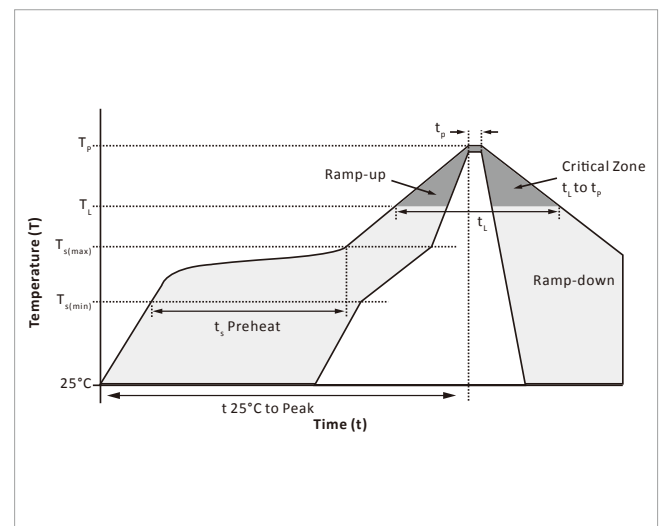
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{RWM}	Reverse Stand-off Voltage				6.5	V
V_{BR}	Reverse Breakdown Voltage	$I_T=1mA$	6.8			V
I_R	Reverse Leakage Current	$V_{RWM}=6.5V$			1	μA
V_C	Clamping Voltage ($T_p=8/20\mu s$)	$I_{pp}=87A, t_p=8/20\mu s$			12.5	V
I_{pp}	Peak Pulse Current ($T_p=8/20\mu s$)	$t_p=8/20\mu s$			87	A
C_J	Off State Junction Capacitance	$V_R=0V, f=1MHz$		550		pF

CHARACTERISTIC CURVES

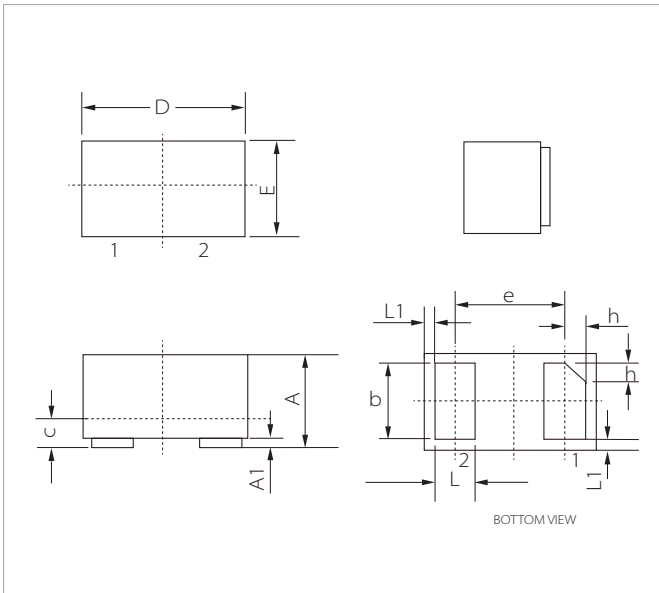


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

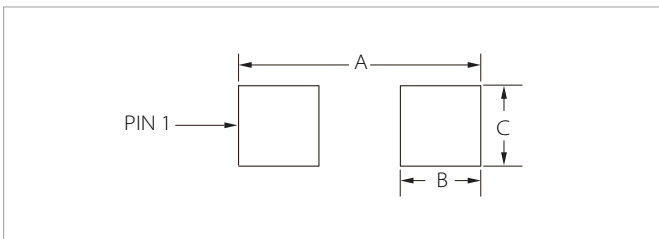


DFN1610 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.45	0.55	0.018	0.022
A1	0	0.05	0	0.002
b	0.75	0.85	0.030	0.033
c	0.10	0.20	0.004	0.008
D	1.55	1.65	0.061	0.065
e	1.10TYP		0.043TYP	
E	0.95	1.05	0.037	0.041
L	0.35	0.45	0.014	0.018
L1	0.05REF		0.002REF	
h	0.15	0.25	0.006	0.010

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
A	1.85	0.073
B	0.625	0.025
C	1.00	0.039

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE16F110U6.5A	DFN1610	3000PCS	7"

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